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1973

Development of side-brazed packages

~ Packaging ~

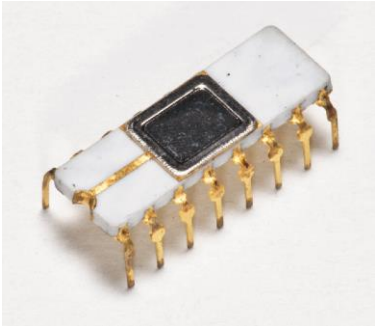
As the density of memory devices increased around 1973, the chip size became larger and it became difficult to assemble it in the package of the conventional structure. The technical team of Musashi Works of Hitachi developed a side-brazed package that attached a lead frame to the side of the ceramic body in which a larger memory chip could be assembled.

Side blaze structure packages were outsourced to ceramic package manufacturers such as Kyocera as the production volume increased, and they started to be sold to other semiconductor manufacturers in and out of Japan from these package manufacturers.

The pictures shown below are, from left to right, the conventional product, a side blaze package manufactured by Hitachi, and a side-blazed package by Kyocera.

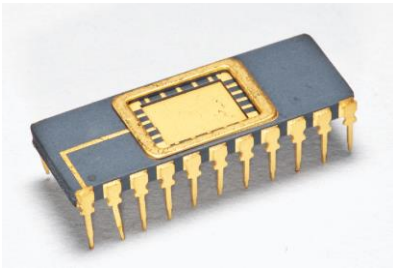
Example of old structure DILC memory, 300 mil column pitch

Hitachi



Column pitch 400 mil type 22 pin ceramic package

Hitachi



Kyocera

